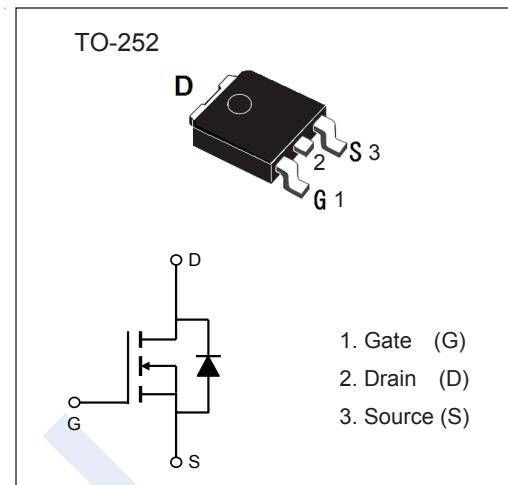


## N-Channel MOSFET

## 2KK5092

## ■ Features

- $V_{DS} = 40 \text{ V}$
- $I_D (\text{at } V_{GS}=10\text{V}) = 70 \text{ A}$
- $R_{DS(\text{ON})} (\text{at } V_{GS} = 10 \text{ V}) < 3.0 \text{ m}\Omega$
- $R_{DS(\text{ON})} (\text{at } V_{GS} = 4.5 \text{ V}) < 3.8 \text{ m}\Omega$
- 100% UIS Tested
- 100%  $R_g$  Tested

■ Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current	$I_D$	70	A
		55	
Pulsed Drain Current (Note 2)	$I_{DM}$	300	
Continuous Drain Current	$I_{DSM}$	23	
		18	
Avalanche Current (Note 2)	$I_{AS}$	68	A
Avalanche Energy $L = 0.1\text{mH}$ (Note 2)	$E_{AS}$	231	mJ
Thermal Resistance, Junction- to-Ambient (Note 5)	$R_{\theta JA}$	47	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction- to-Case	$R_{\theta JC}$	1	
Power Dissipation (Note 4)	$P_D$	150	W
		75	
Power Dissipation (Note 5)	$P_{DSM}$	2.7	
		1.7	
Junction Temperature	$T_J$	175	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-55 to 175	

Notes:

1. The maximum current rating is package limited.
2. Single pulse width limited by junction temperature  $T_J(\text{MAX})=175^\circ\text{C}$ .
3. The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to case  $R_{\theta JC}$  and case to ambient.
4. The power dissipation  $P_D$  is based on  $T_J(\text{MAX})=175^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
5. The value of  $R_{\theta JA}$  is measured with the device mounted on  $1\text{in}^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ . The Power dissipation  $P_{DSM}$  is based on  $R_{\theta JA} t \leq 10\text{s}$  and the maximum allowed junction temperature of  $175^\circ\text{C}$ . The value in any given application depends on the user's specific board design.

## N-Channel MOSFET

## 2KK5092

■ Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{Id} = 250 \mu\text{A}, \text{V}_{\text{GS}} = 0\text{V}$	40			V
Zero Gate Voltage Drain Current	$\text{Id}_{\text{SS}}$	$\text{V}_{\text{DS}} = 40 \text{ V}, \text{V}_{\text{GS}} = 0 \text{ V}$			1	$\mu\text{A}$
		$\text{V}_{\text{DS}} = 40 \text{ V}, \text{V}_{\text{GS}} = 0 \text{ V}, T_J = 55^\circ\text{C}$			5	
Gate to Source Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{DS}} = 0 \text{ V}, \text{V}_{\text{GS}} = \pm 20 \text{ V}$			$\pm 100$	nA
Gate to Source Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{Id} = 250 \mu\text{A}$	1.0		2.2	V
Static Drain-Source On-Resistance	$\text{R}_{\text{DS(on)}}$	$\text{V}_{\text{GS}} = 10 \text{ V}, \text{Id} = 20 \text{ A}$		2.3	3.0	$\text{m}\Omega$
		$\text{V}_{\text{GS}} = 10 \text{ V}, \text{Id} = 20 \text{ A}, T_J = 125^\circ\text{C}$		3.6	4.8	
		$\text{V}_{\text{GS}} = 4.5 \text{ V}, \text{Id} = 20 \text{ A}$		2.8	3.8	
Forward Transconductance	$\text{g}_{\text{FS}}$	$\text{V}_{\text{DS}} = 5 \text{ V}, \text{Id} = 20 \text{ A}$		78		S
<b>Dynamic Characteristics</b>						
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{GS}} = 0 \text{ V}, \text{V}_{\text{DS}} = 20 \text{ V}, f = 1 \text{ MHz}$		3510	4300	$\text{pF}$
Output Capacitance	$\text{C}_{\text{oss}}$			1070		
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$			68		
Gate Resistance	$\text{R}_g$	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=0\text{V}, f = 1\text{MHz}$	0.5	1	1.5	$\Omega$
<b>Switching Characteristics</b>						
Total Gate Charge (10V)	$\text{Q}_g$	$\text{V}_{\text{GS}} = 10 \text{ V}, \text{V}_{\text{DS}} = 20 \text{ V}, \text{Id} = 20 \text{ A}$		49	60	$\text{nC}$
Total Gate Charge (4.5V)	$\text{Q}_{\text{gs}}$			22		
Gate Source Charge	$\text{Q}_{\text{gd}}$			9		
Gate Drain Charge	$\text{Q}_{\text{gd}}$			7		
Turn-On Delay Time	$\text{t}_{\text{d(on)}}$	$\text{V}_{\text{GS}} = 10 \text{ V}, \text{V}_{\text{DS}} = 20 \text{ V}, \text{RL} = 1 \Omega, \text{R}_{\text{GEN}} = 3 \Omega$		11		$\text{ns}$
Turn-On Rise Time	$\text{t}_r$			10		
Turn-Off Delay Time	$\text{t}_{\text{d(off)}}$			38		
Turn-Off Fall Time	$\text{t}_f$			11		
<b>Drain-Source Diode Characteristics</b>						
Body Diode Reverse Recovery Time	$\text{t}_{\text{rr}}$	$\text{I}_{\text{F}} = 20 \text{ A}, \text{dI/dt} = 500 \text{ A}/\mu\text{s}$		21		$\text{ns}$
Body Diode Reverse Recovery Charge	$\text{Q}_{\text{rr}}$			58		
Maximum Body-Diode Continuous Current	$\text{I}_{\text{S}}$	(Note 1)			70	A
Diode Forward Voltage	$\text{V}_{\text{SD}}$	$\text{V}_{\text{GS}} = 0 \text{ V}, \text{Is} = 1 \text{ A}$		0.65	1	V

Notes:

- The static characteristics in Figures 1 to 6 are obtained using  $<300\mu\text{s}$  pulses, duty cycle 0.5% max.
- These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of  $T_{J(\text{MAX})}=175^\circ\text{C}$ . The SOA curve provides a single pulse rating.
- These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ .

## ■ Marking

Marking	K5092 KC***
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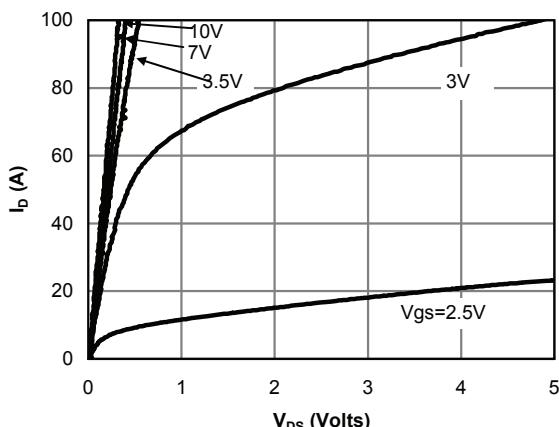
**N-Channel MOSFET****2KK5092****■ Typical Electrical And Thermal Characteristics**

Fig 1: On-Region Characteristics (Note 6)

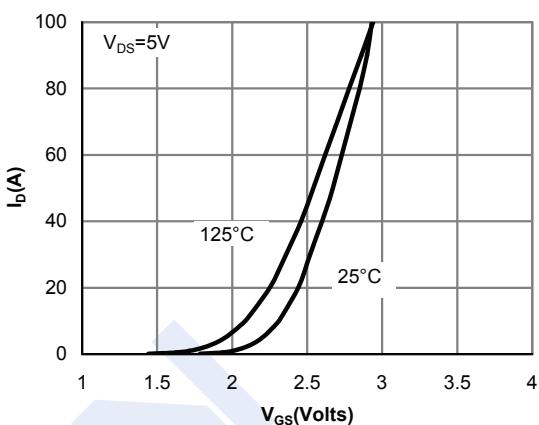


Figure 2: Transfer Characteristics (Note 6)

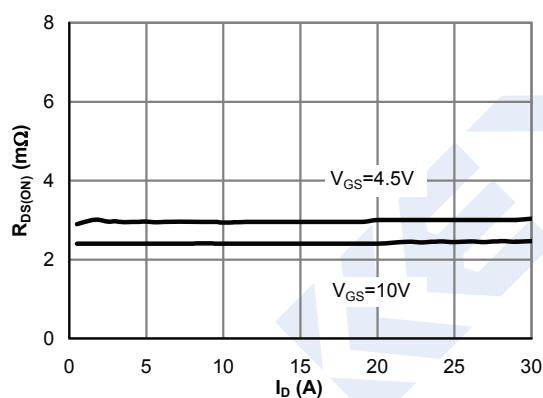


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note 6)

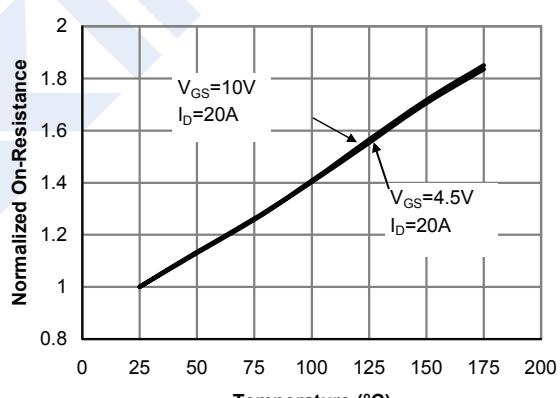


Figure 4: On-Resistance vs. Junction Temperature (Note 6)

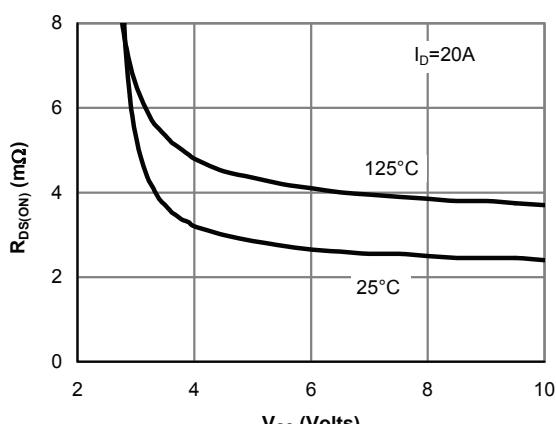


Figure 5: On-Resistance vs. Gate-Source Voltage (Note 6)

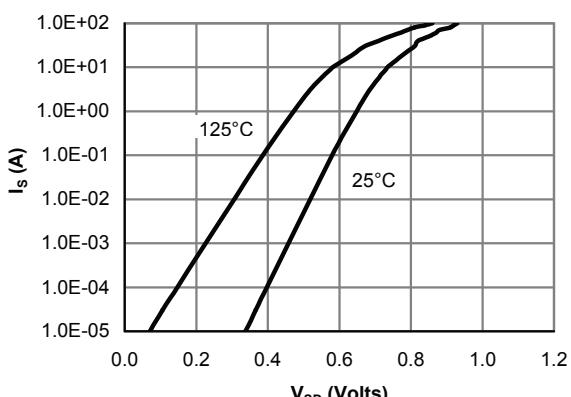
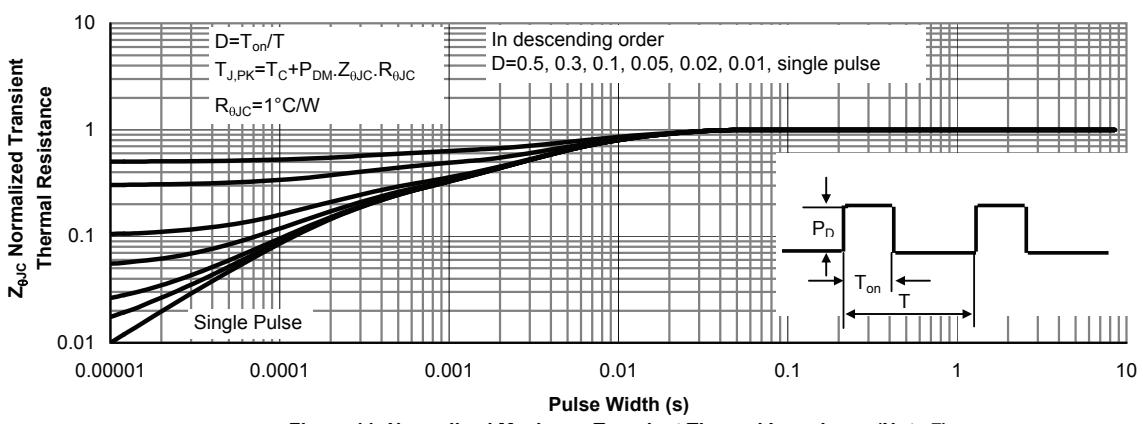
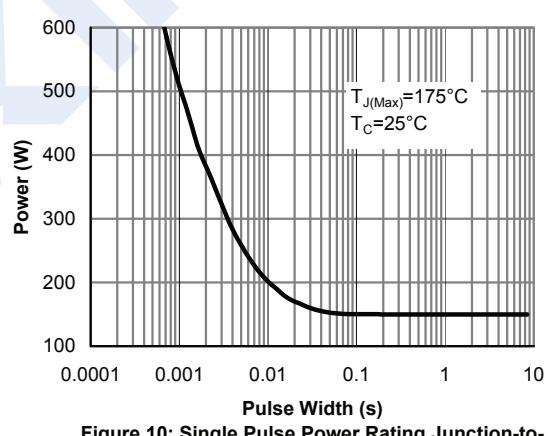
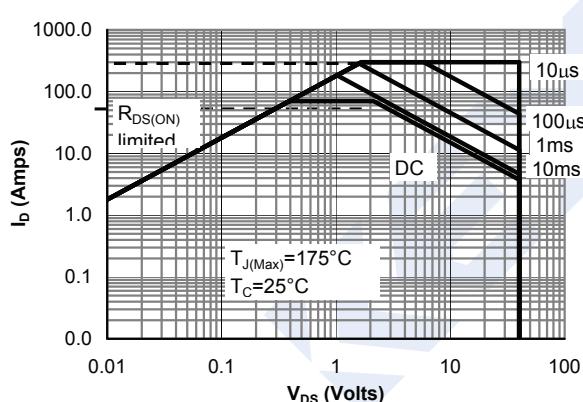
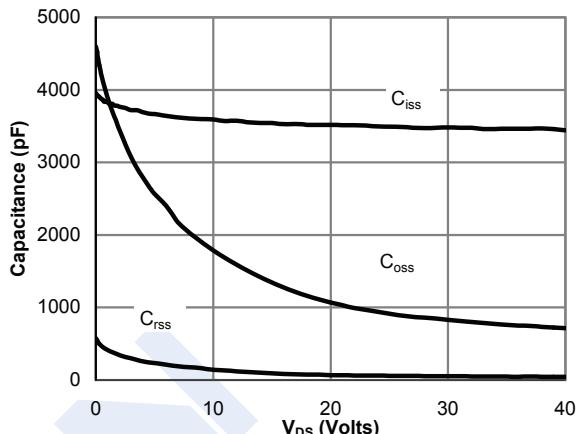
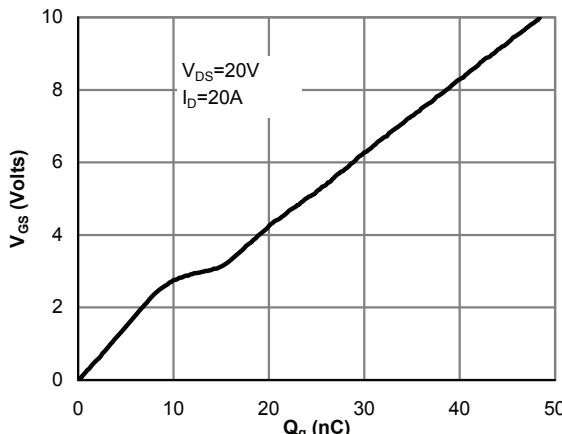


Figure 6: Body-Diode Characteristics (Note 6)

## N-Channel MOSFET

### 2KK5092



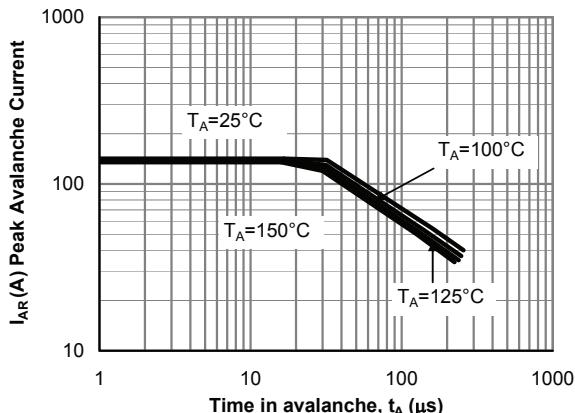
**N-Channel MOSFET****2KK5092**

Figure 12: Single Pulse Avalanche capability

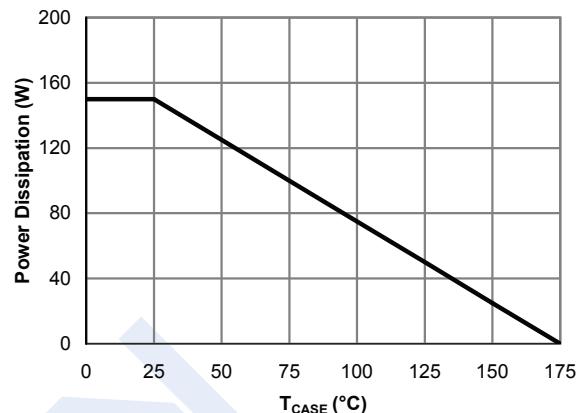


Figure 13: Power De-rating (Note 7)

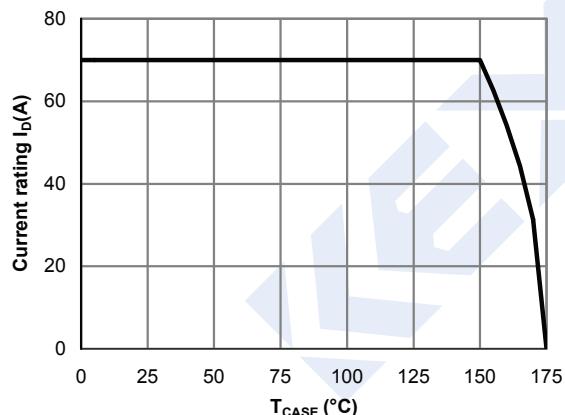


Figure 14: Current De-rating (Note 7)

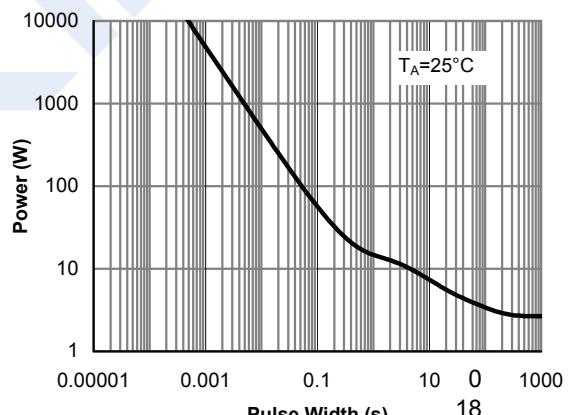


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note 8)

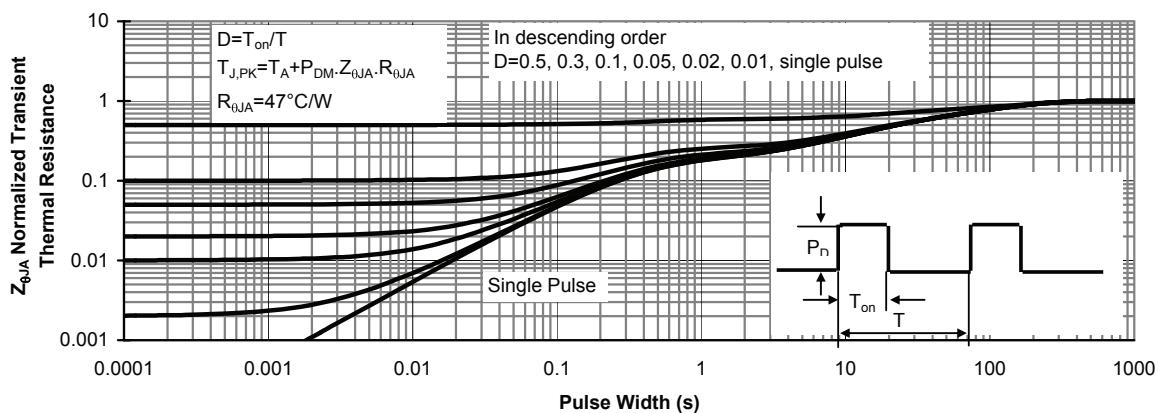
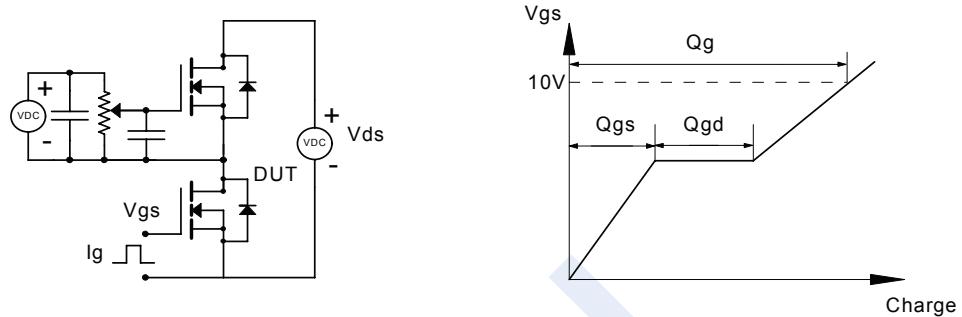


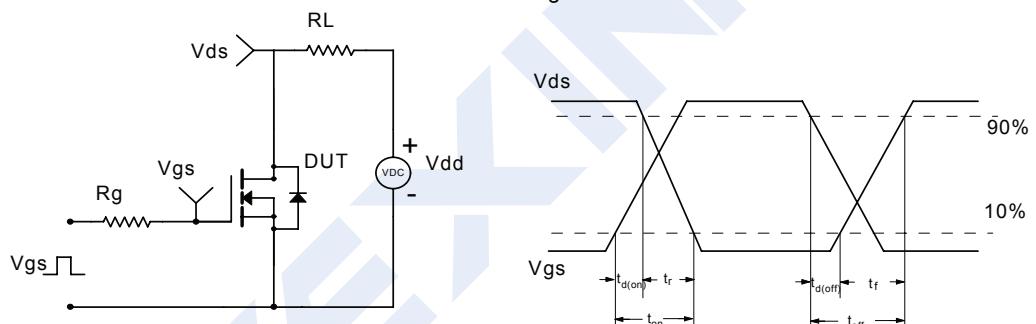
Figure 16: Normalized Maximum Transient Thermal Impedance (Note 8)

**N-Channel MOSFET****2KK5092**

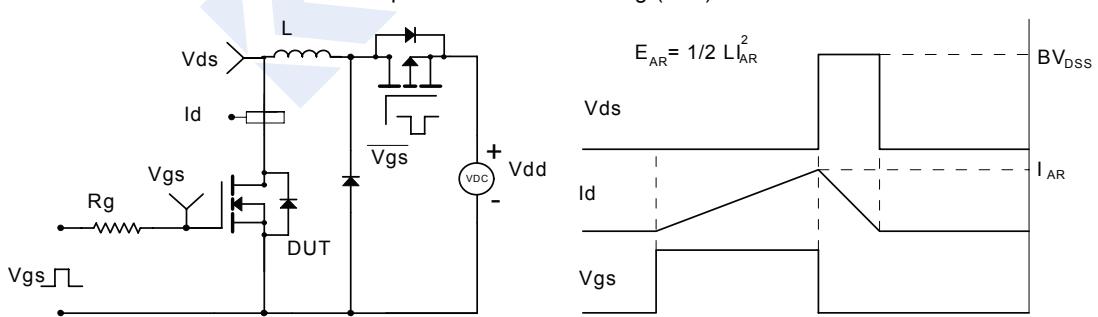
Gate Charge Test Circuit &amp; Waveform



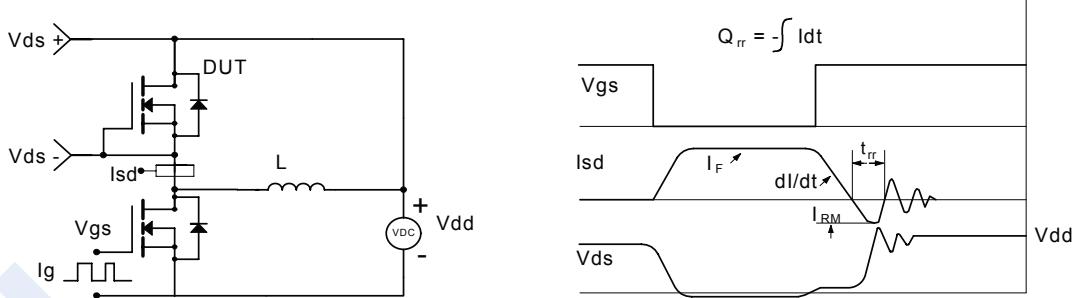
Resistive Switching Test Circuit &amp; Waveforms



Unclamped Inductive Switching (UIS) Test Circuit &amp; Waveforms



Diode Recovery Test Circuit &amp; Waveforms

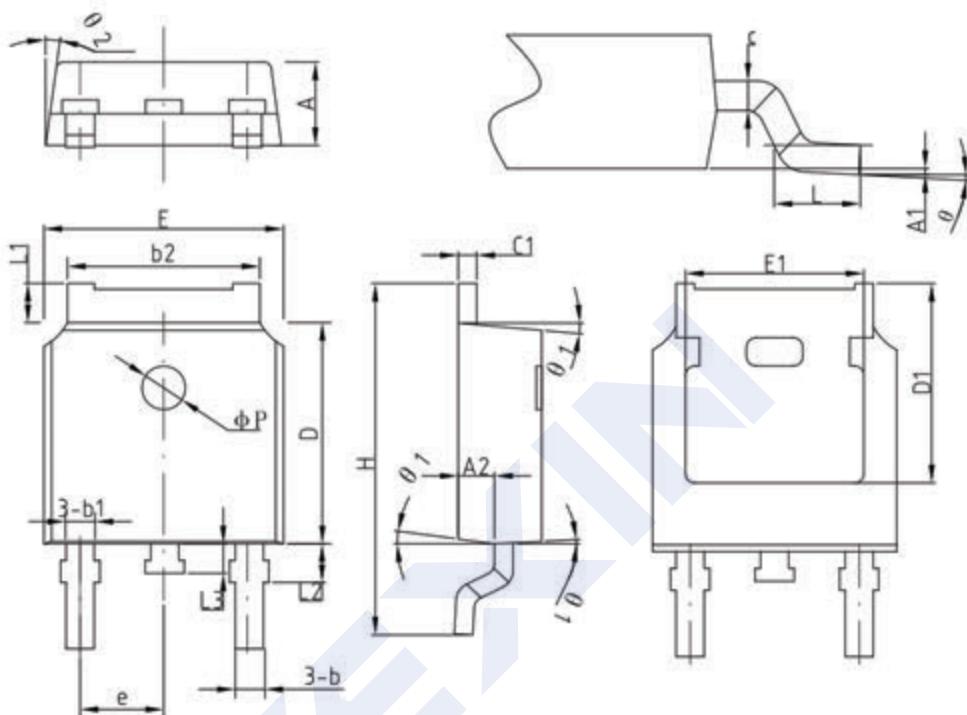


**N-Channel MOSFET****2KK5092**

## ■ Package Dimension

TO-252

Units: mm



**COMMON DIMENSIONS**  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	2.2	2.30	2.38
A1	0	—	0.10
A2	0.90	1.01	1.10
b	0.71	0.76	0.86
b1		0.76	
b2	5.13	5.33	5.46
c	0.47	0.50	0.60
c1	0.47	0.50	0.60
D	6.0	6.10	6.20
D1	—	5.30	—
E	6.50	6.60	6.70
E1	—	4.80	—
e		2.286BSC	
H	9.70	10.10	10.40
L	1.40	1.50	1.70
L1	0.90	—	1.25
L2		1.05	
L3		0.8	
φP		1.2	
θ	0°	—	8°
θ1	5°	7°	9°
θ2	5°	7°	9°